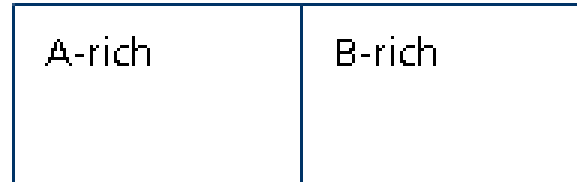


Diffusion in Substitutional Alloys

❖ Binary substitutional diffusion



D_A, D_B (intrinsic diffusion coefficient): diffusion relative to the lattice

J_A, J_B : across a given lattice plane (moving)

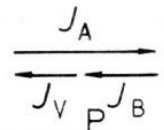
$$J_A = -D_A \frac{\partial C_A}{\partial x}, \quad J_B = -D_B \frac{\partial C_B}{\partial x}$$

Total # of atoms/unit volume = C_o (constant, independent of composition)

Then, $C_o = C_A + C_B$

$$\frac{\partial C_A}{\partial x} = -\frac{\partial C_B}{\partial x}$$

$$J_A = -D_A \frac{\partial C_A}{\partial x}, \quad J_B = +D_B \frac{\partial C_A}{\partial x}$$

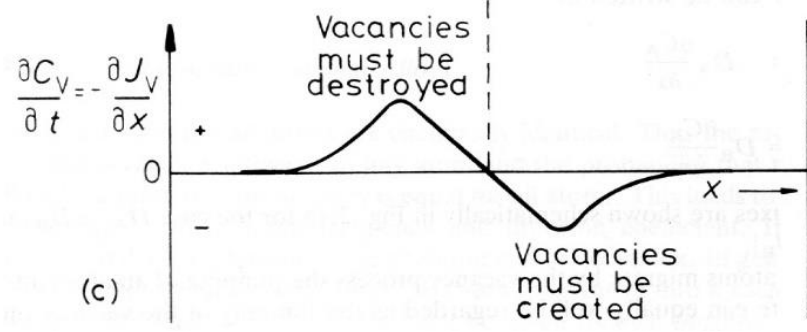
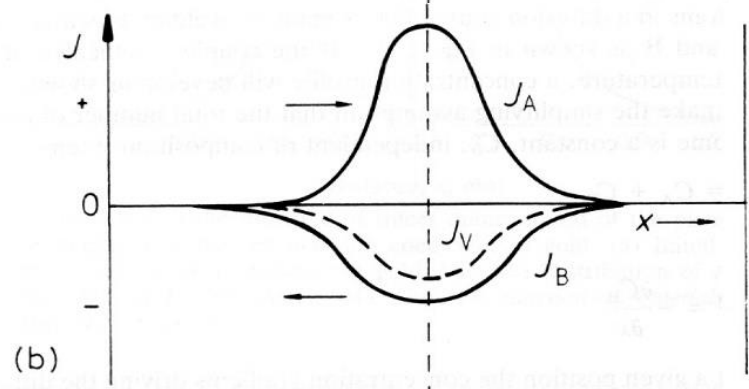
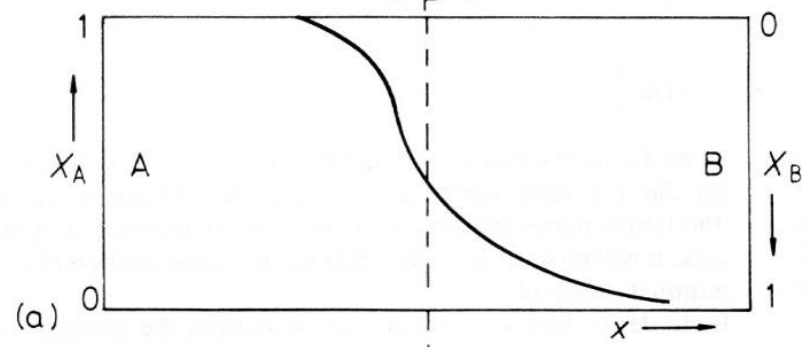


$$J_A = -D_A \frac{\partial C_A}{\partial x}, \quad J_B = +D_B \frac{\partial C_A}{\partial x}$$

If $D_A > D_B$, then $J_A > J_B$

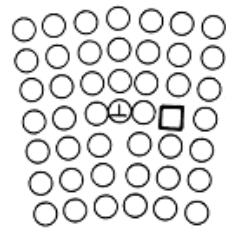
$$J_v = -J_A - J_B = (D_A - D_B) \frac{\partial C_A}{\partial x} \quad \dots \quad (1)$$

variation in J_v across the diff. couple



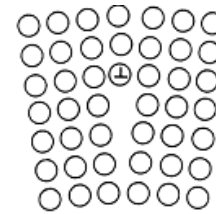
Supersaturated vacancies

→ Equilibrium should be maintained by **dislocation motion**



(a)

dislocation climb-up

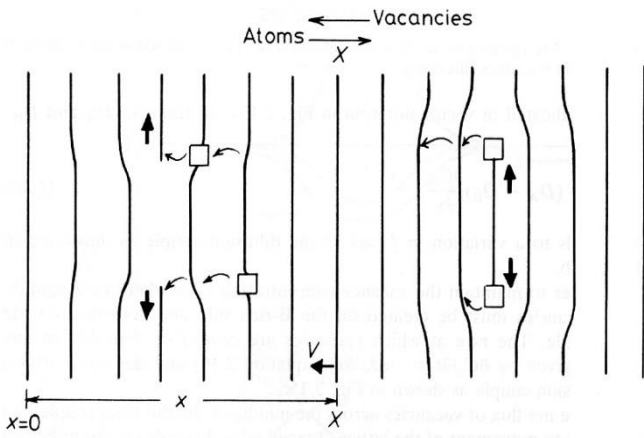


(b)

dislocation climb-down

lattice plane **destroyed**

lattice plane **created**



⇒ **Movement of lattice**

- Velocity of the lattice plane : v
- Volume swept out ($Av\delta t$) contains ($Av\delta tC_0$) atoms
= total # of vacancy crossing the plane ($J_v A \delta t$)

$$\therefore J_v = C_0 v \quad \dots \dots (2)$$

from (1) and (2)

$$v = (D_A - D_B) \frac{\partial X_A}{\partial x}$$

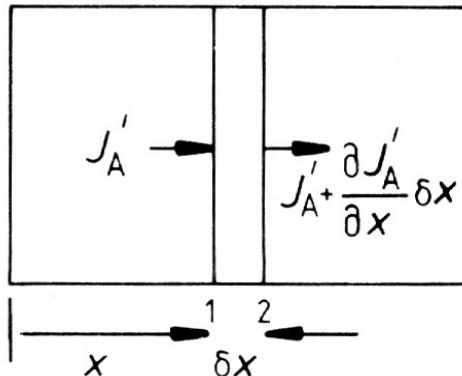
$$X_A (= \frac{C_A}{C_0} = \text{mole fraction of } A)$$

$$v = (D_A - D_B) \frac{\partial X_A}{\partial x}$$

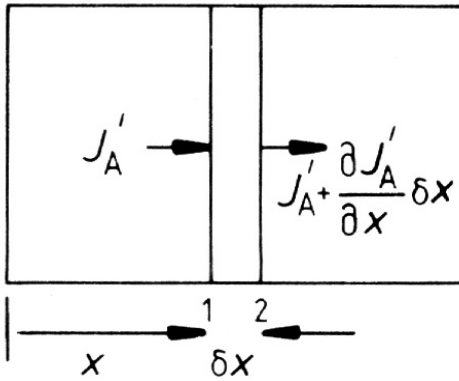
Practical question

- (1) Time for homogenization
- (2) Change in composition at a fixed position relative to the end of specimen

- **Variation in J_v across the diffusion couple.**



Total flux of A across a stationary plane with respect to specimen
 = a diffusing flux ($J_A = -D_A \frac{\partial C_A}{\partial x}$) w.r.t. lattice
 + flux due to lattice (vC_A)



Total flux of A across a stationary plane with respect to specimen
 = a diffusing flux ($J_A = -D_A \frac{\partial C_A}{\partial x}$) w.r.t. lattice
 + flux due to lattice (vC_A)

$$\begin{aligned}
 J_A' &= -D_A \frac{\partial C_A}{\partial x} + vC_A \\
 &= -D_A \frac{\partial C_A}{\partial x} + C_A (D_A - D_B) \frac{\partial X_A}{\partial x} \\
 &= -D_A \frac{\partial C_A}{\partial x} + (X_A D_A - X_B D_B) \frac{\partial C_A}{\partial x} \\
 &= -(X_B D_A - X_A D_B) \frac{\partial C_A}{\partial x}
 \end{aligned}$$

$$J_A' = -\tilde{D} \frac{\partial C_A}{\partial x}, \quad \tilde{D} = (X_B D_A + X_A D_B)$$

→ **Interdiffusion coefficient**

Likewise
$$J_{B'} = -\tilde{D} \frac{\partial C_B}{\partial x} = \tilde{D} \frac{\partial C_A}{\partial x} \quad \text{i.e.} \quad J_{B'} = J_{A'}$$

Using continuity equation,

$$\frac{\partial C_A}{\partial t} = -\frac{\partial J_{A'}}{\partial x}$$

$$\frac{\partial C_A}{\partial t} = \frac{\partial}{\partial x} \left(\tilde{D} \frac{\partial C_A}{\partial x} \right)$$

Fick's 2nd law for substitutional alloy Darken's Eq

As long as the range of comp. is small

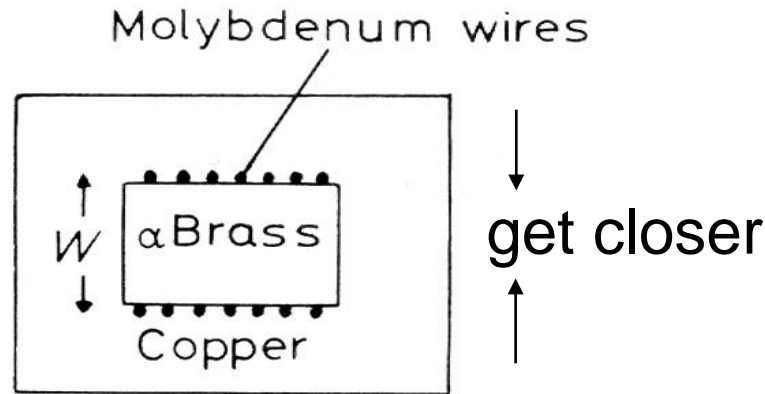
$$X_A D_B + X_B D_A \approx D_B, \quad \tilde{D} \neq f(\text{comp.})$$

to know D_A, D_B , need to know v (by marker)

with known v & $\tilde{D} \Rightarrow D_A, D_B$

$$\tilde{D} = \tilde{D}_0 \exp\left(-\frac{Q}{RT}\right) \quad \text{likewise,} \quad D_A = D_{A0} \exp\left(-\frac{Q_A}{RT}\right)$$

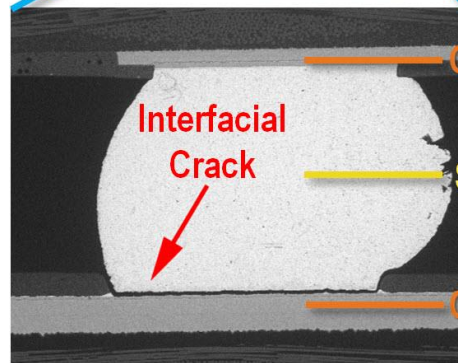
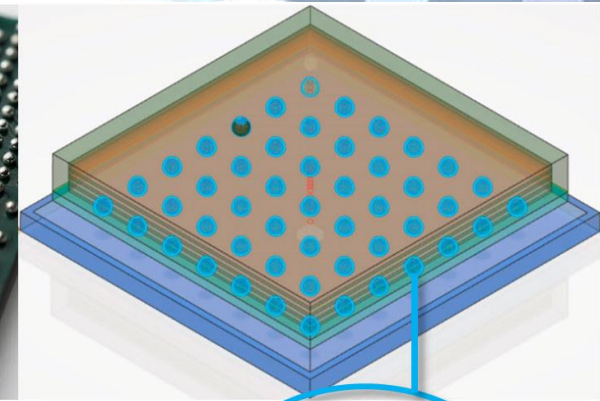
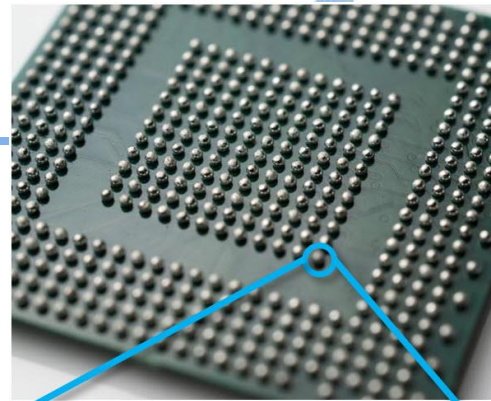
Kirkendall Effect



- $D_{Zn} > D_{Cu}$
 - Lower melting point materials (low atomic size) has higher D .
1. For a given crystal structure, $\tilde{D}(T_m) = \text{const.}$ in if B was added to A, results in lower T_{m2} than $\tilde{D}(T_{m2})$ (after B added) will be higher than before.
 2. Open structure \rightarrow higher diff.

Interstitial C in Fe	$D_c^\alpha / D_c^\gamma \sim 100$
Sub. Self diff	$D_{Fe}^\alpha / D_{Fe}^\gamma \sim 100$

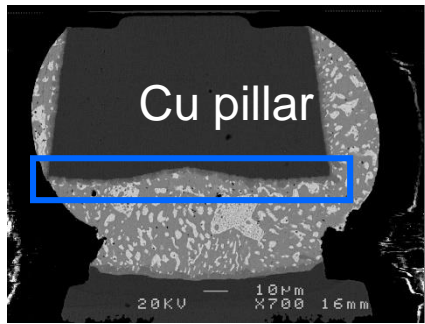
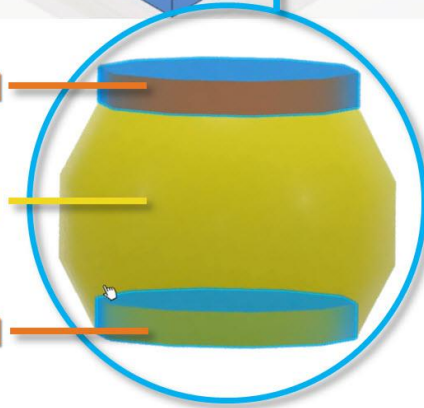
Kirkendall void



Copper Pad

Solder Ball

Copper Pad



As reflowed

180hr

120°C

300hr



Kirkendall voids formed at the interface between Cu and solder.

